

DESCRIPTION

The SPP9433W is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

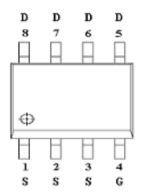
FEATURES

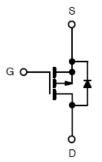
- -30V/-6A, RDS(ON)= $42m\Omega$ @VGS=-10V
- -30V/-3 A,RDS(ON)= $78m\Omega(@)VGS=-4.5V$
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOP-8P package design

APPLICATIONS

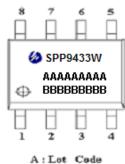
- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- LCD Display inverter

PIN CONFIGURATION(SOP - 8P)





PART MARKING



B : Date Code

IN DESCRIPTION					
Pin	Symbol	Description			
1	S	Source			
2	S	Source			
3	S	Source			
4	G	Gate			
5	D	Drain			
6	D	Drain			
7	D	Drain			
8	D	Drain			

ORDERING INFORMATION

Part Number	Package	Part Marking
SPP9433WS8RGB	SOP- 8P	SPP9433W

^{*} SPP9433WS8RGB: 13" Tape Reel; Pb – Free; Halogen - Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage	Vdss	-30	V	
Gate –Source Voltage	VGSS	±20	V	
Continuous Drain Current(Tj=150°C)	TA=25°C	ID	-6	А
Continuous Diani Current (13–130 C)	Ta=70°C	ID	-4	A
Pulsed Drain Current		Ірм	-12	А
Continuous Source Current(Diode Conductio	Is	-6	А	
Power Dissipation	TA=25°C	PD	2.08	W
Operating Junction Temperature	Тл	-55/150	$^{\circ}\mathbb{C}$	
Storage Temperature Range	Tstg	-55/150	$^{\circ}\mathbb{C}$	
Thermal Resistance-Junction to Ambient	RθJA	60	°C/W	

Page 2

ELECTRICAL CHARACTERISTICS

(Ta=25°C Unless otherwise noted)

Parameter	Symbol	Symbol Conditions		Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS	V _G s=0V,I _D =-250uA	-30			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=-250uA	-1.0		-2.5]	
Gate Leakage Current	Igss	V _{DS} =0V,V _{GS} =±20V			±100	nA	
		V _{DS} =-24V,V _{GS} =0V			-1		
Zero Gate Voltage Drain Current	Idss	V _{DS} =-24V,V _{GS} =0V T _J =55°C			-5	uA	
On-State Drain Current			-6			A	
Dunin Course On Booleton	Drac	Vgs=- 10V,Ip=-6A		0.035	0.042		
Drain-Source On-Resistance	RDS(on)	V _{GS} =- 4.5V,I _D =-3A		0.065	0.078	Ω	
Forward Transconductance	gfs	V _{DS} =-10.0V,I _D =-6A		6		S	
Diode Forward Voltage	Vsd	Is=-6A,VGS=0V			-1.2	V	
Dynamic							
Total Gate Charge	Qg			6.4			
Gate-Source Charge	Qgs	V _{DS} =-20V, V _{GS} =-4.5V I _D =-6A		2.7		nC	
Gate-Drain Charge	Qgd	-110 -071		3.1			
Input Capacitance	Ciss			650			
Output Capacitance	Coss	V _{DS} =-24V,V _{GS} =0V f=1MHz		270		pF	
Reverse Transfer Capacitance	Crss			104			
T. O. T.	td(on)			9		ns	
Turn-On Time	tr	VDD=-12V, ID=-5.0A,		16			
T. OMT.	td(off)	$V_{GEN}=-10V$ RG=3.3 Ω		21			
Turn-Off Time	tf			22			





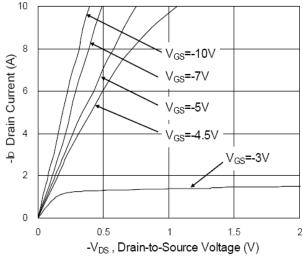


Fig. 1 Typical Output Characteristics

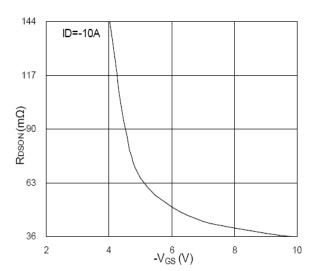


Fig. 2 On-Resistance vs. Gate Voltage

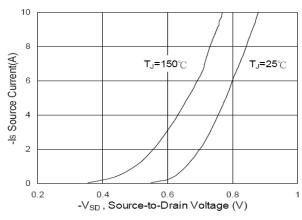


Fig. 3 Forward characteristics of Diodes

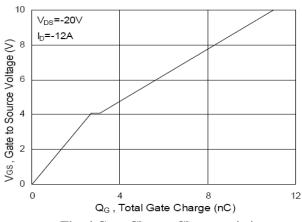


Fig. 4 Gate Charge Characteristics

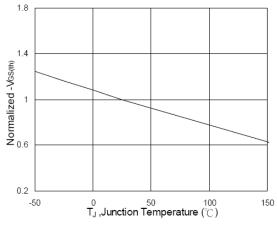


Fig. 5 Vgs vs. Junction Temperature

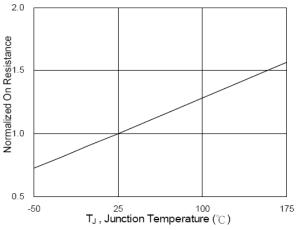
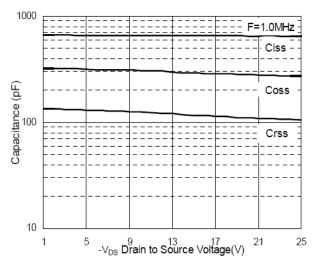


Fig. 6 On-Resistance vs Junction Temp

2011/05/30 **Ver.1**

TYPICAL CHARACTERISTICS



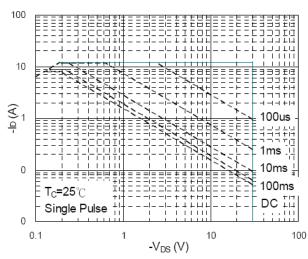


Fig. 7 Typical Capacitance Characteristics

Fig. 8 Maximum Safe Operation Area

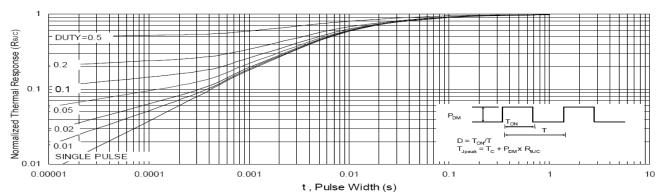
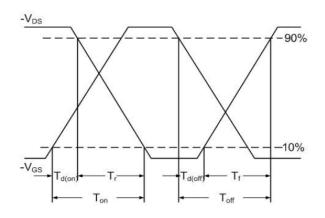


Fig. 9 Effective Transient Thermal Impedance



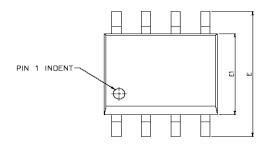
EAS= 1/2 L x (-I_{AS}²)x -BV_{DSS} -V_{DD} -V_{DD}

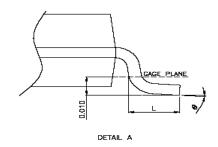
Fig. 10 Switching Time Waveform

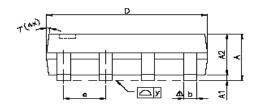
Fig. 11 Unclamped Inductive Waveform

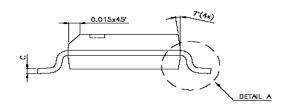


SOP- 8 PACKAGE OUTLINE









0.4.400.40	DIMENSIONS IN MILLIMETERS		DIMENSIONS IN INCHES			
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10		0.25	0.004		0.010
A2		1.45			0.057	
Ь	0.33	0.41	0.51	0.013	0.016	0.020
С	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
Е	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
е		1.27			0.050	
L	0.38	0.71	1.27	0.015	0.028	0.050
<u>∕</u> 2 y			0.076			0.003
0	0°		8°	0,		8*

Information provided is alleged to be exact and consistent. SYNC Power Corporation presumes no responsibility for the penalties of use of such information or for any violation of patents or other rights of third parties which may result from its use. No license is granted by allegation or otherwise under any patent or patent rights of SYNC Power Corporation. Conditions mentioned in this publication are subject to change without notice. This publication surpasses and replaces all information previously supplied. SYNC Power Corporation products are not authorized for use as critical components in life support devices or systems without express written approval of SYNC Power Corporation.

©The SYNC Power logo is a registered trademark of SYNC Power Corporation
©2011 SYNC Power Corporation – Printed in Taiwan – All Rights Reserved
SYNC Power Corporation
7F-2, No.3-1, Park Street
NanKang District (NKSP), Taipei, Taiwan 115
Phone: 886-2-2655-8178
Fax: 886-2-2655-8468

©http://www.syncpower.com